Display Elektronik GmbH

DATA SHEET

LCD-MODULE

DEM 20489 SBH-PW-N

Product Specification

Ver.: 3

Revision History

VERSION	DATE	Note
0	12.12.2011	First Issue
1	28.11.2012	Modify Backlight Information
2	19.08.2014	Remove IC Information
3	25.02.2016	Modify Precautions in use of LCD Modules
		& Static Electricity Test

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1. General Specification

The Features is described as follow:

■ Module Dimension: 74.30 x 36.40 x 6.00 mm

■ View Area: 60.50 x 22.18 mm

Active Area: 58.50 x 20.18 mm

■ Dot Size: 0.45x 0.54 mm

■ Dot Pitch: 0.50 x 0.59 mm

■ Character Size: 2.45 x 4.67 mm

■ Character Pitch: 2.95 x 5.17 mm

■ LCD Type: STN-BLUE Negative Transmissive

■ Duty: 1/33DUTY,1/6BIAS

■ View Direction: 6 o'clock

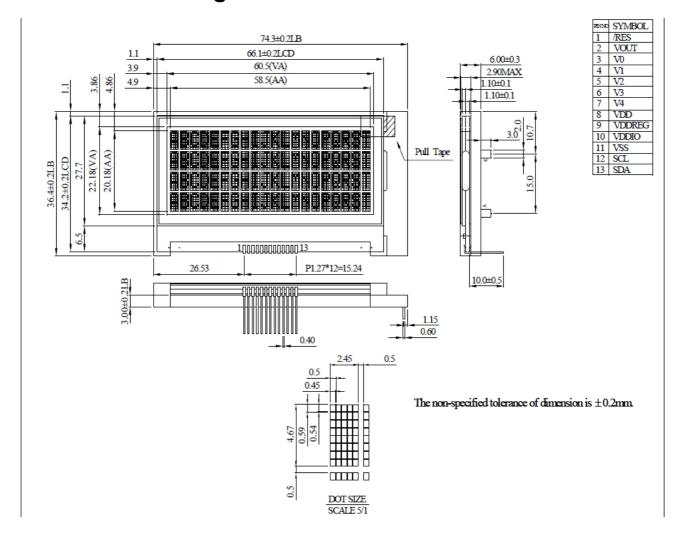
■ Backlight Type: LED, White

■ IC: SSD1803AM1Z

2. Interface Pin Function

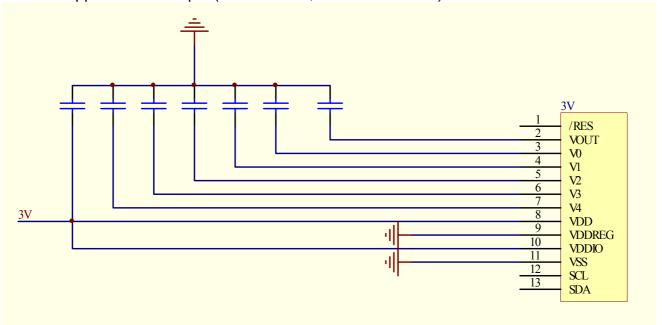
Pin No.	Symbol	Description			
1	/RES	Reset Pin			
2	VOUT	Output of the voltage converter			
_		Regulated voltage from voltage converter for			
3	V0	LCD driving			
4	V1				
5	V2	Bias voltage levels for LCD driving			
6	V3	Blas voltage levels for ECD driving			
7	V4				
8	VDD	This pin is the power supply for logic circuit (VDD should rise within 10ms). In 3V IO application (VDDREG pulled low), this is a power input pin. In 5V IO application (VDDREG pulled high), this pin outputs 3V and should be connected with a capacitor to VSS.			
9	VDDREG	This pin is used to enable VDD regulator in 5V I/O Application: VDDREG Mode			
10	VDDIO	This pin is the power supply for bus IO buffer in both Low Voltage I/O and 5V I/O application.			
11	VSS	Ground			
12	SCL	This pin is used as clock input pin in I2C mode.			
13	SDA	This pin is used as data/ acknowledge response output pin in I2C mode.			

3. Counter Drawing

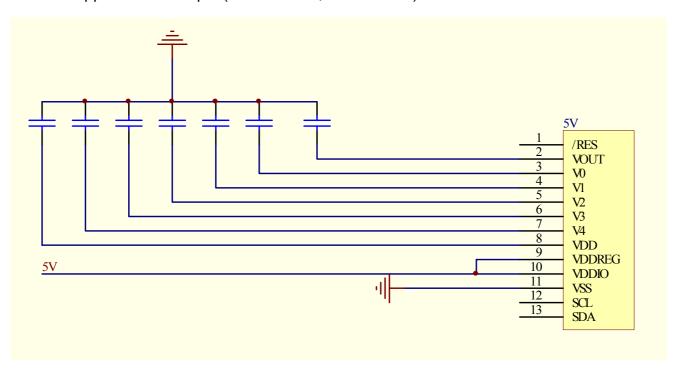


DEM 20489 SBH-PW-N3.1 APPLICATION EXAMPLES

3.1.1 Application Example (I2C interface, 3V VDDIO mode)



3.1.2 Application Example (I2C interface, 5V IO mode)



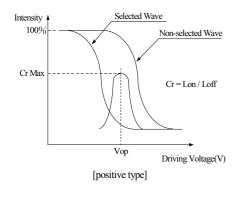
Capacitance =1µF

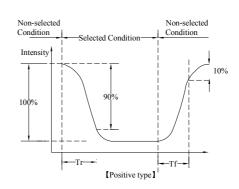
4. Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
	θ	CR ≧ 2	0		20	ψ= 180°
Viou Anglo	θ	CR ≧ 2	0	_	40	ψ= 0°
View Angle	θ	CR ≧ 2	0	_	30	ψ= 90°
	θ	CR ≧ 2	0	_	30	ψ= 270°
Contrast Ratio	CR	_	_	3	_	_
Decrease Time	T Rise	_	_	150	200	ms
Response Time	T Fall	_	_	150	200	ms

Definition of Operation Voltage (Vop)

Definition of Response Time (Tr, Tf)



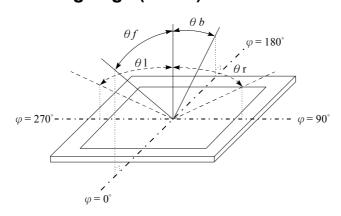


Conditions:

Operating Voltage : Vop Viewing Angle (θ, ϕ) : 0° , 0°

Frame Frequency: 64 Hz Driving Waveform: 1/N duty, 1/a bias

Definition of viewing angle(CR≥2)



5. Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	TOP	-20	_	+70	°C
Storage Temperature	TST	-30	_	+80	°C
Input Voltage	VIN	-0.3	_	V _{DD} +0.3	V
Power Supply Voltage	V_{DD}	-0.3	_	6.0	V
LCD Driver Voltage	VLCD	-0.3	_	15.0	V

6. Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
		Low Voltage		2.0		\
Constant Valta as Faul ania	V_{DDIO}	I/O App.	2.4	3.0	V _{DD}	V
Supply Voltage For Logic		5V I/O App.	4.5	5.0	5.5	V
	V_{DD}	_	2.4	3.0	3.6	V
		Ta=-20°C	_	_	_	V
Supply Voltage For LCD	Vo-Vss	Ta=25°C	7.6	7.8	8.0	V
		Ta=70°C	_	_	_	V
Input High Volt.	VIH	_	0.8 V _{DDIO}	_	V _{DDIO}	V
Input Low Volt.	VIL	_	_	_	0.2 V _{DDIO}	V
Output High Volt.	V _{OH}	_	0.8 V _{DDIO}	_	V _{DDIO}	V
Output Low Volt.	V _{OL}	_	_	_	0.2 V _{DDIO}	V
Supply LCM current	IDD	VDD=3.0V	_	1.0	2.0	mA

Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance.

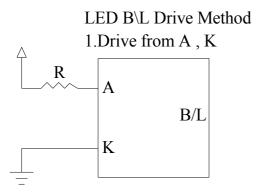
7. Backlight Information

Specification

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION	
Supply Current	ILED	_	48	60	mA	V=3.5V	
Supply Voltage	V	3.4	3.5	3.6	V	_	
Reverse Voltage	VR	_	_	5	V	_	
Luminance	IV	560	700		CD/M ²	ILED=48mA	
(Without LCD)	IV	360	700		CD/IVI-	ILED-40IIIA	
LED Life Time						ILED=48mA	
(For Reference	_	_	50000	_	Hr.	25°C, 50-60%RH,	
only)						(Note 1)	
Color	White						

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Note 1: 50000 hours is only an estimate for reference.



8. Reliability

Content of Reliability Test (Wide temperature, -20°C~+70°C)

Environmental Test						
Test Item	Content of Test	Test Condition	Note			
High Temperature storage	Endurance test applying the high storage temperature for a long time.	200hrs	2			
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2			
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	+70°C 200hrs				
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1			
High Temperature/ Humidity storage	The module should be allowed to stand at 60□,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	+60°C,90%RH 96hrs	1,2			
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C +25°C +70°C 30min 5min 30min 1 cycle	-20°C/+70°C 10 cycles				
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3			
Static electricity test	Endurance test applying the electric stress to the terminal.	VS= ± 600 V(Contact), ± 800 v(Air), RS= 330Ω CS= 150 pF 10 times				

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

9. Inspection specification

NO	Item	Criterion					
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. 					
02	Black or white spots on LCD (display only)	three white o	 2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm 				
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type $\Phi = (x + y) / $ $X \longrightarrow X$ 3.2 Line type : (2 ↓ ▼ Y	SIZE $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$	Acceptable Q TY Accept no dense 2 1 0 Acceptable Q TY Acceptable Q TY Accept no dense 2 As round type	2.5	
04	Polarizer bubbles	If bubbles are vijudge using black specifications, reto find, must che specify direction	ck spot not easy eck in	Size Φ $ Φ \le 0.20 $ $ 0.20 < Φ \le 0.50 $ $ 0.50 < Φ \le 1.00 $ $ 1.00 < Φ $ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3	2.5	

NO	Item		Criterion		AQL
05	Scratches	Follow NO.3 LCD black	spots, white spots, con	tamination	
06	Chipped glass	Symbols Define: x: Chip length y: 0	Chip width z: Chip Glass thickness a: LCI grade and crack between y: Chip width Not over viewing area Not exceed 1/3k chips, x is total length of y: Chip width Not over viewing	thickness D side length n panels: x: Chip length x≤ 1/8a x≤ 1/8a	2.5
		1/2t <z≦2t< td=""><td>area Not exceed 1/3k</td><td>x≦1/8a</td><td></td></z≦2t<>	area Not exceed 1/3k	x≦1/8a	
		⊙If there are 2 or more			
			onips, x is the total left	gui oi eacii cilip.	

NO	Item		Criterion		AQL
NO 06	Glass	k: Seal width t: Glass L: Electrode pad length 6.2 Protrusion over terminal 6.2.1 Chip on electrode pad y: Chip width y≤0.5mm 6.2.2 Non-conductive portion y: Chip width y≤ L o If the chipped area must remain and be specifications.	x: Chip length z x ≤ 1/8a x: Chip length z x ≤ 1/8a x: Chip length z x ≤ 1/8a touches the ITO terminate inspected according to	e length $ \begin{array}{c} Z \\ Z \\$	AQL 2.5
		stomer, the alignment			
		No.	y: width y≤1/3L	x: length x ≤ a	
		y w	8		

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB · COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB 	2.5 2.5 0.65 2.5 0.65 2.5 2.5
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
		12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.12.2 No cracks on interface pin (OLB) of TCP.	2.5 0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to	2.5
	General	sever.	2.5
12	appearance	12.6 The residual rosin or tin oil of soldering (component or chip	
	опри сентенто	component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened.	0.65
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on	
		packaging specification sheet.	0.65
		12.11 Product dimension and structure must conform to product specification sheet.	
		12.12 Visual defect outside of VA is not considered to be rejection.	

10. Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3) Don't disassemble the LCM.
- (4) Don't operate it above the absolute maximum rating.
- (5) Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) DISPLAY have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) DISPLAY have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, DISPLAY have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 minutes of fixed display content.